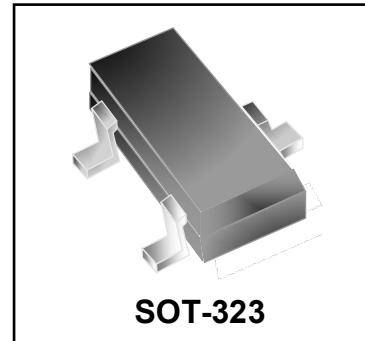


Features

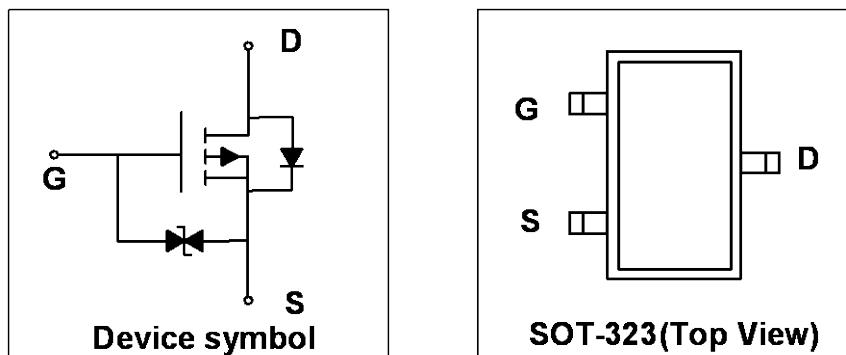
- Way-on Small Signal MOSFETs
- $V_{DS} = -50V$, $I_D = -0.2A$
- $R_{DS(on)} < 3\Omega$ @ $V_{GS} = -10V$
- $R_{DS(on)} < 4\Omega$ @ $V_{GS} = -4.5V$
- Trench LV MOSFET Technology
- ESD Protected



Mechanical Characteristics

- SOT-323 Package
- Marking : Making Code
- RoHS Compliant

Schematic & PIN Configuration



Absolute Maximum Rating ($T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Value	Units
Drain-Source Voltage		V_{DS}	-50	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A=25^\circ C$	I_D	-0.2	A
Pulsed Drain Current ¹		I_{DM}	-0.8	A
Power Dissipation	$T_A=25^\circ C$	P_D	300	mW
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Units
Thermal Resistance from Junction to Ambient ²	$R_{\theta JA}$	416.6	°C/W

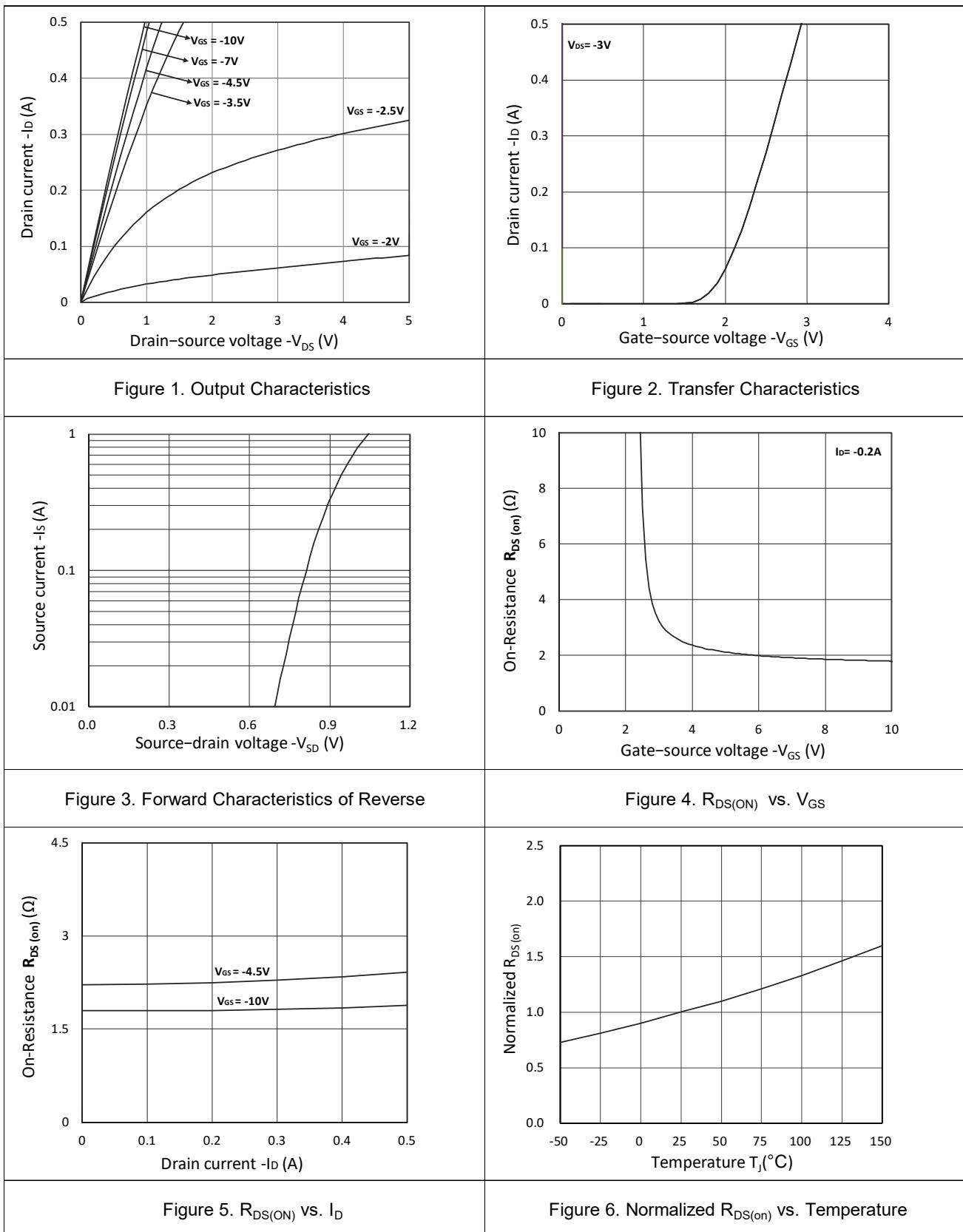
Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-50	-	-	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±10	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -50V, V _{GS} = 0V	-	-	-1	μA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.5	-2	V
Drain-Source on-State Resistance ³	R _{DS(on)}	V _{GS} = -10V, I _D = -0.2A	-	1.8	3	Ω
		V _{GS} = -4.5V, I _D = -0.1A	-	2.2	4	
Dynamic Characteristics⁴						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = -25V, f=1MHz	-	26.5	-	pF
Output Capacitance	C _{oss}		-	5.5	-	
Reverse Transfer Capacitance	C _{rss}		-	4	-	
Switching Characteristics⁴						
Total Gate Charge	Q _g	V _{GS} = -10V, V _{DS} = -25V, I _D = -0.2A	-	1.5	-	nC
Gate-Source Charge	Q _{gs}		-	0.35	-	
Gate-Drain Charge	Q _{gd}		-	0.6	-	
Turn-on Delay time	t _{d(on)}	V _{GS} = -10V, V _{DD} = -25V , R _G = 3Ω, I _D = -0.2A	-	1.7	-	ns
Rise Time	t _r		-	0.6	-	
Turn-off Delay Time	t _{d(off)}		-	10	-	
Fall Time	t _f		-	5.5	-	
Source-Drain Diode Characteristics						
Body Diode Voltage ³	V _{SD}	I _S = -0.2A, V _{GS} = 0V	-	-	-1.2	V
Continuous Source Current	I _S	-	-	-	-0.2	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width≤300μs, duty cycle≤2%.
4. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics



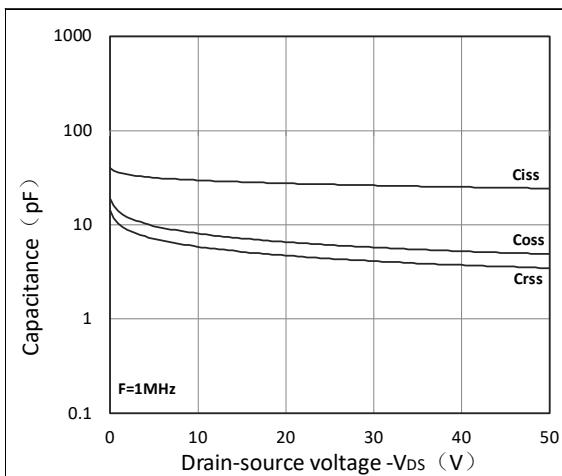


Figure 7. Capacitance Characteristics

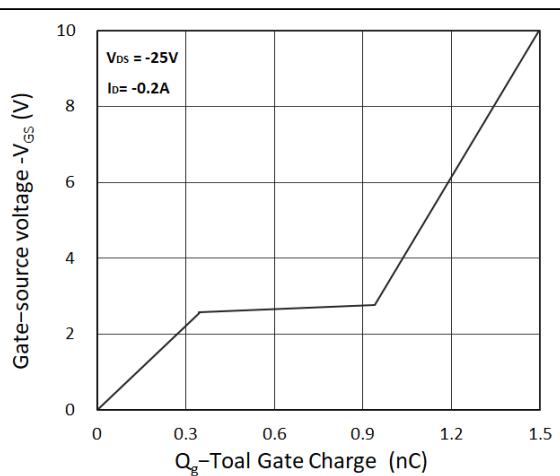
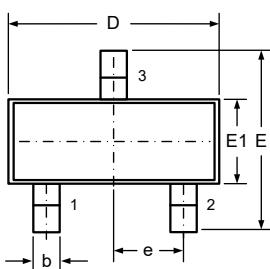
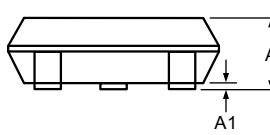
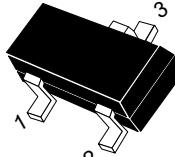


Figure 8. Gate Charge Characteristics

Outline Drawing – SOT-323

PACKAGE OUTLINE		SOT-323			
 		 SOT-323			
SYMBOL	DIMMETER		INCHES		
	MIN	MAX	MIN	MAX	
A	0.90	1.10	0.035	0.043	
A1	0.00	0.10	0.000	0.004	
D	2.00	2.20	0.079	0.087	
b	0.20	0.40	0.008	0.016	
c	0.08	0.15	0.003	0.006	
E	2.15	2.45	0.085	0.096	
E1	1.15	1.35	0.045	0.053	
e	0.65TYP		0.026TYP		
L	0.525 REF		0.021 REF		
θ	0	8°	0	8°	

DIMENSIONS		
DIM	INCHES	MILLIMETERS
M	0.076	1.90
C	0.036	0.9
Z	0.110	2.8
e	0.026	0.65
e1	0.052	1.30
b	0.028	0.7

Notes

- Dimensioning and tolerances per ANSI Y14.5M, 1985.
- Controlling Dimension: Inches
- Pin 3 is the cathode (Unidirectional Only).
- Dimensions are exclusive of mold flash and metal burrs.

Marking Codes

Part Number	WM05P02G
Marking Code	

Package Information

Qty: 3k/Reel

CONTACT INFORMATION

No.1001, Shiwan (7) Road, Pudong District, Shanghai, P.R.China.201207

Tel: 86-21-68969993 Fax: 86-21-50757680 Email: market@way-on.com

WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

WAYON ® is registered trademark of Wayon Corporation.

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.